

Havok

Part No: PCS.06.A

Description

Low Profile LTE/Cellular 4G/3G/2G SMD Dielectric Antenna

PCS.06.A BASE PC

Features:

SMD Dielectric Antenna 698~960MHz/1710~2690MHz High Efficiency SMD antenna Low profile 42*10*3mm RoHS & Reach Compliant



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Introduction

1.



The Havok PCS.06.A is a low profile SMD LTE/cellular 4G/3G/2G embedded antenna designed for direct SMD mount on a device PCB. It provides high efficiency in a very small factor 42*10*3mm. If tuning is required it can be tuned for the device environment, while there is no need for new tooling.

Its rectangular shape and small size makes it very easy to integrate – packaged in tape and reel, it can be mounted via pick and place to reflow solder directly on the edge of the PCB board. This antenna is recommended to be used with long ground-plane lengths of 120mm or more to attain its highest rated efficiency, note the return loss and efficiency graphs.

Typical Applications Include:

- Connected Health
- Handheld Devices
- Wearables

The antenna is suitable for lower cost LTE/cellular applications due to the ease of integration. Contact your regional Taoglas customer support team for quick and professional support from our senior engineering team on integration and matching of the antenna to your device.



Specification

2.

	LTE Electrical							
Band	Frequency (MHz)	Efficiency (%)	Average Gain (dB)	Peak Gain (dBi)	Impedance	Polarization	Radiation Pattern	Max. input power
5GNR/4G Band71	617-698	27.3	-5.64	-0.22				
4G/3G Band 12,13,14,17,28,29	698-806	65.3	-1.85	2.60				
4G/3G/NB-IoT/Cat M Band 5,8,18,19,20,26,27	824-960	61.5	-2.11	2.22	50 Ω	Linear	Omni	2W
4G/3G Band 1,2,3,4,9,23,25,35,39,6 6	1710-2200	69.1	-1.61	5.93				
4G/3G Band 7,30,38,40,41	2300-2690	58.2	-2.35	4.35				

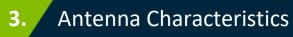
Mechanical			
Antenna Dimensions42mm x 10mm x 3mm			
Material	FR4		
Weight	2.50g		
Soldering Type	SMD Reflow		

Environmental		
Operation Temperature	-40°C ~ +85°C	
Storage Temperature	-40°C ~ +85°C	
Moisture Sensitivity Level	3	

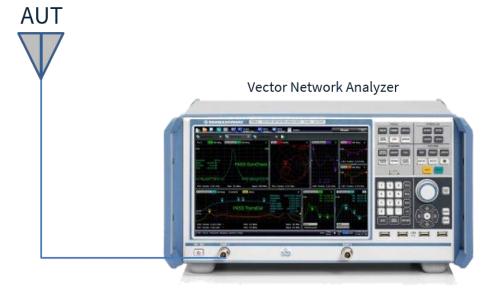


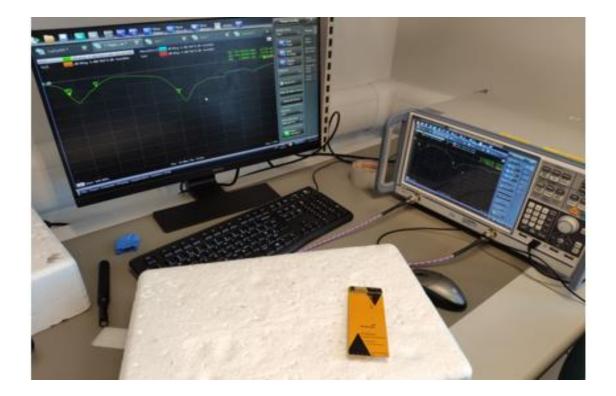
	5G/4G	Bands	
Band Number	5GNR / FR1 / LTE	/ LTE-Advanced / WCDMA / HSPA / HS	SPA+ / TD-SCDMA
	Uplink	Downlink	Covered
B1	1920 to 1980	2110 to 2170	✓
B2	1850 to 1910	1930 to 1990	✓
B3	1710 to 1785	1805 to 1880	✓
B4	1710 to 1755	2110 to 2155	✓
B5	824 to 849	869 to 894	✓
B7	2500 to 2570	2620 to 2690	✓
B8	880 to 915	925 to 960	✓
B9*	1749.9 to 1784.9	1844.9 to 1879.9	✓
B11	1427.9 to 1447.9	1475.9 to 1495.9	✓
B12	699 to 716	729 to 746	✓
B13	777 to 787	746 to 756	✓
B14	788 to 798	758 to 768	✓
B17	704 to 716	734 to 746	✓
B18	815 to 830	860 to 875	✓
B19	830 to 845	875 to 890	✓
B20	832 to 862	791 to 821	1
B21	1447.9 to 1462.9	1495.9 to 1510.9	✓
B22*	3410 to 3490	3510 to 3590	*
B23*	2000 to 2020	2180 to 2200	√
B23	1626.5 to 1660.5	1525 to 1559	↓
B24 B25	1850 to 1915	1930 to 1995	↓
B25 B26	814 to 849	859 to 894	↓
B27*			√
	807 to 824	852 to 869	↓
B28	703 to 748	758 to 803	↓
B29		to 728	
B30	2305 to 2315	2350 to 2360	~
B31	452.5 to 457.5	462.5 to 467.5	× √
B32		to 1496	
B34	2010 1	√	
B35	1850 to 1910 1930 to 1990		1
B36			1
B37		to 1930	√
B38		to 2620	×
B39		to 1920	√
B40		co 2400	√
B41		co 2690	1
B42		co 3600	*
B43		to 3800	×
B45		to 1467	✓
B46		to 5925	×
B47		to 5925	×
B48		to 3700	*
B49		to 3700	*
B50		to 1517	×
B51		to 1432	1
B52		to 3400	*
B53		to 2495	√
B65	1920 to 2010	2110 to 2200	√
B66	1710 to 1780	2110 to 2200	V
B68	698 to 728	753 to 783	√
B69		co 2620	×
B70	1695 to 1710	1995 to 2020	\checkmark
B71	663 to 698	617 to 652	×
B72	451 to 456	461 to 466	*
B73	450 to 455	460 to 465	*
B74	1427 to 1470	1475 to 1518	1
B75	1432 1	to 1517	1
B76	1427 1	to 1432	✓
B77	3300 t	to 4200	*
B78	3300 t	to 3800	×
B79	4400 t	to 5000	*
B85	698 to 716	728 to 746	✓
B87	410 to 415	420 to 425	*
B88	412 to 417	422 to 427	*



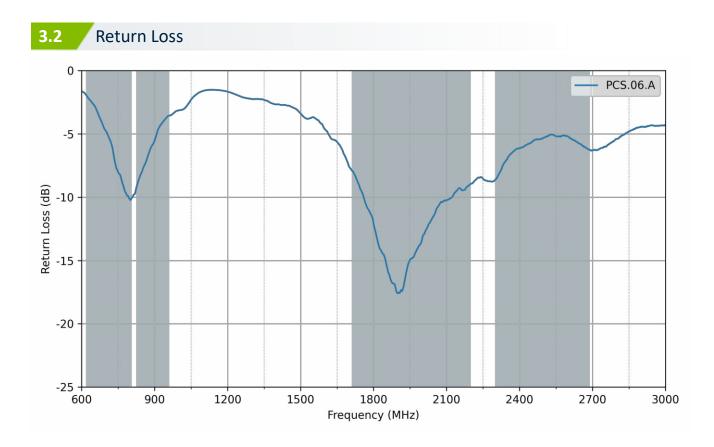


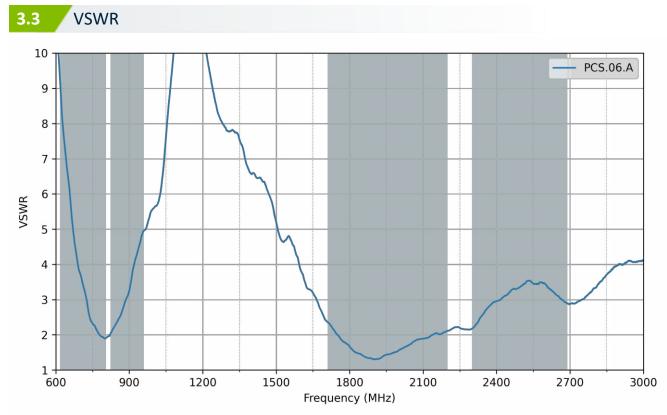




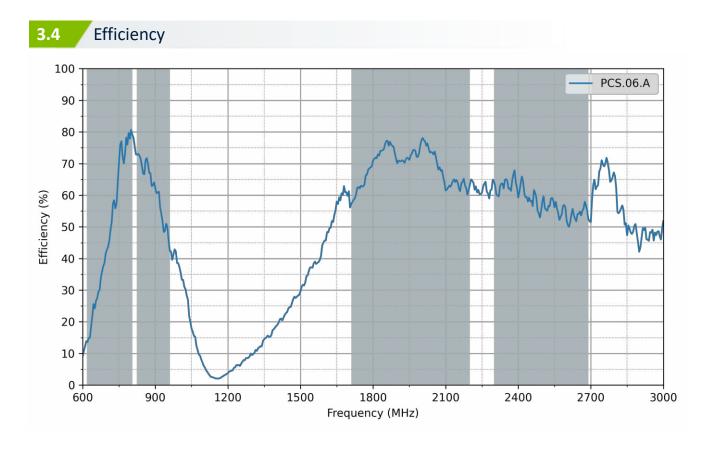


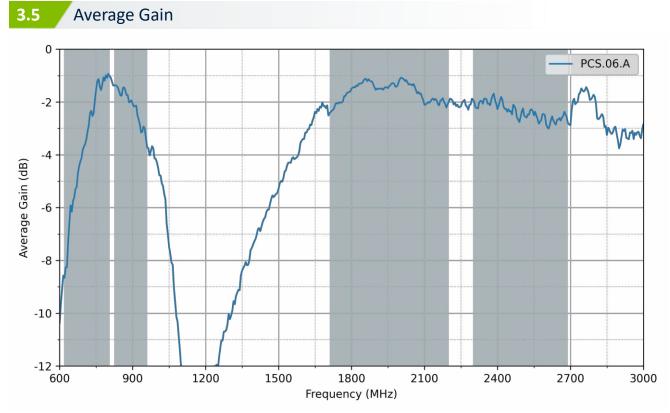




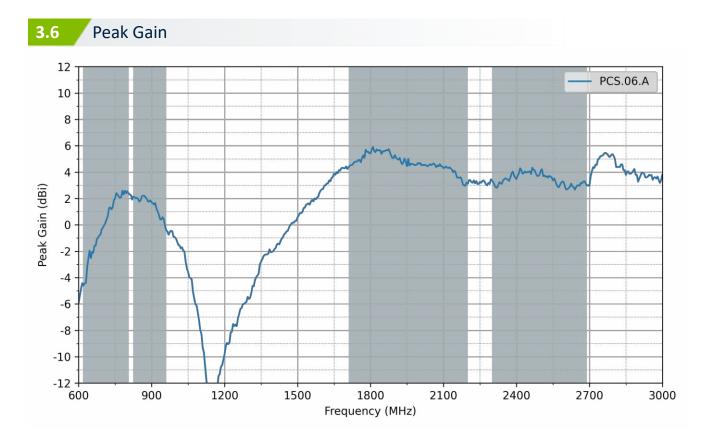










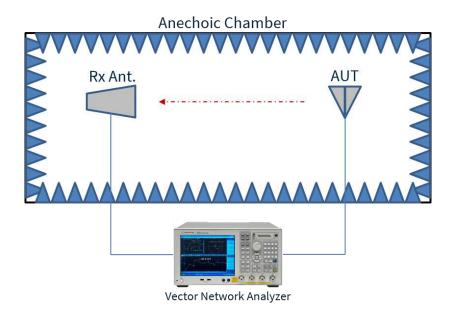


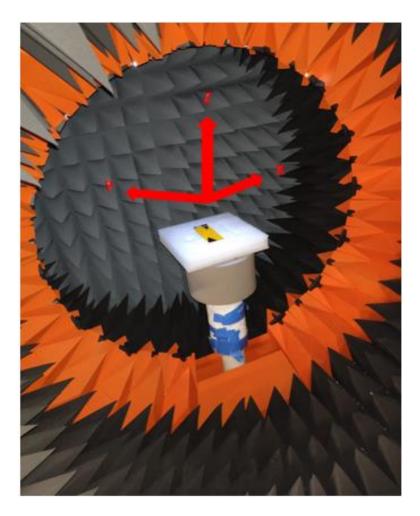






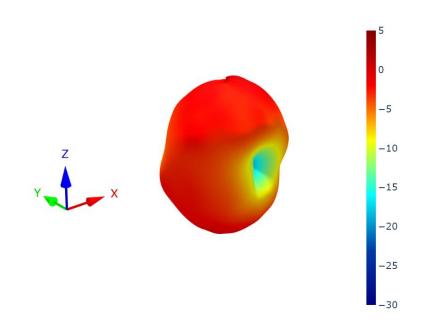
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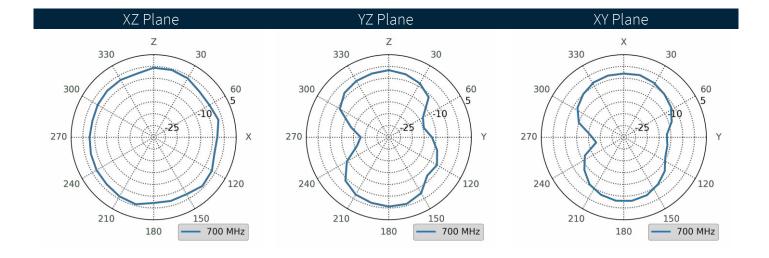




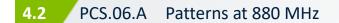


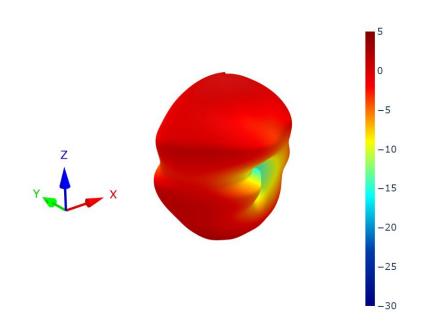


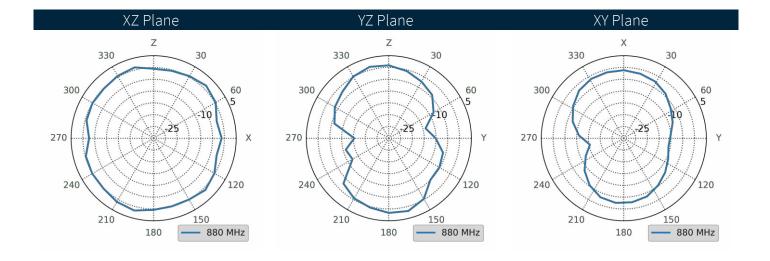






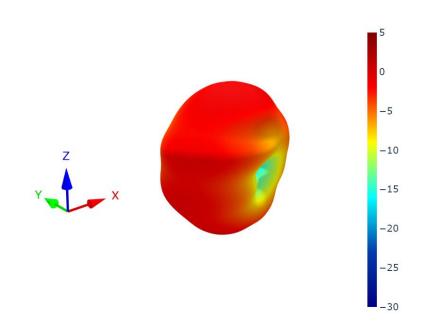


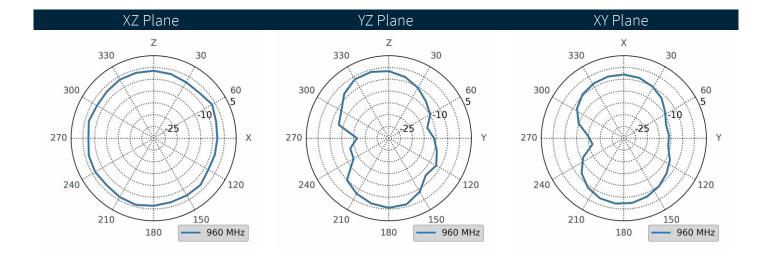




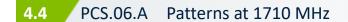


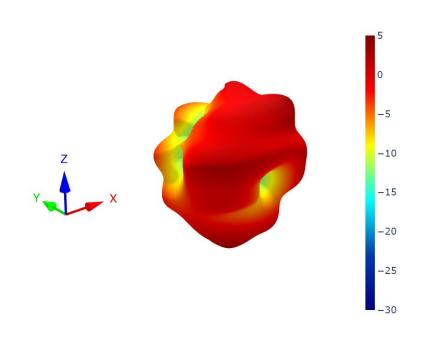


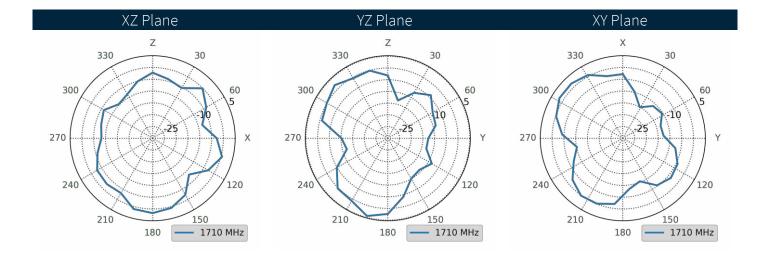






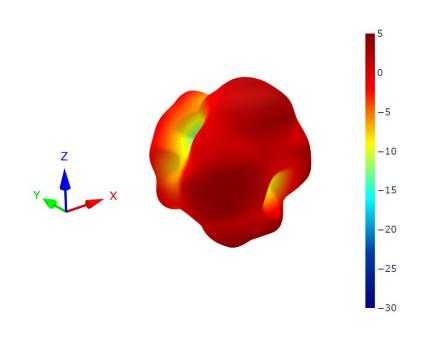


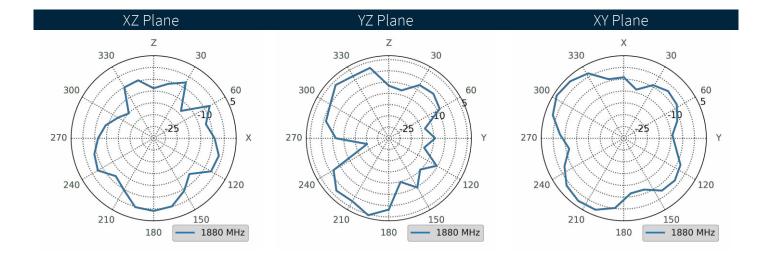






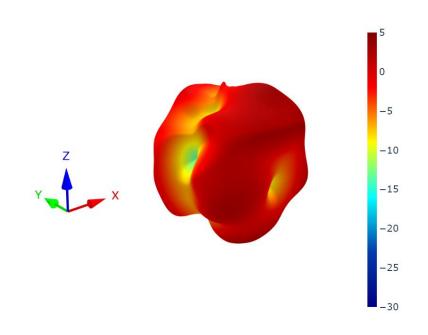


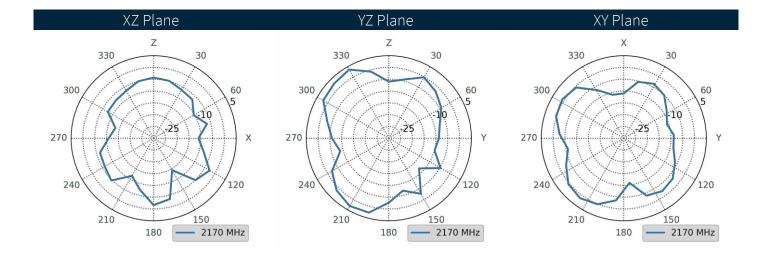






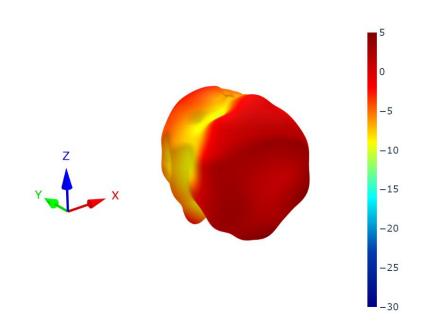


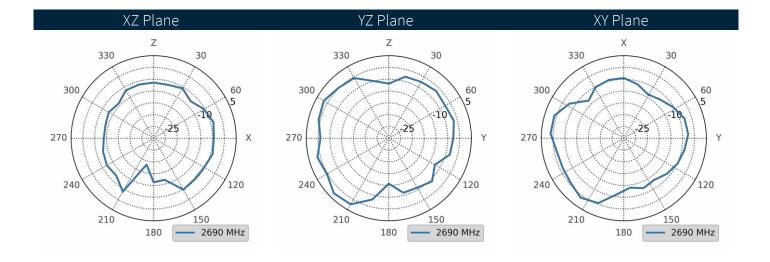






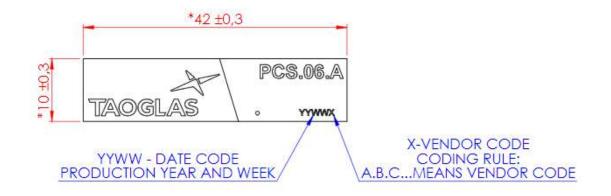




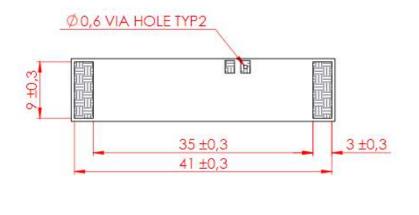


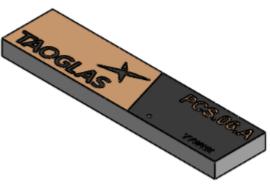


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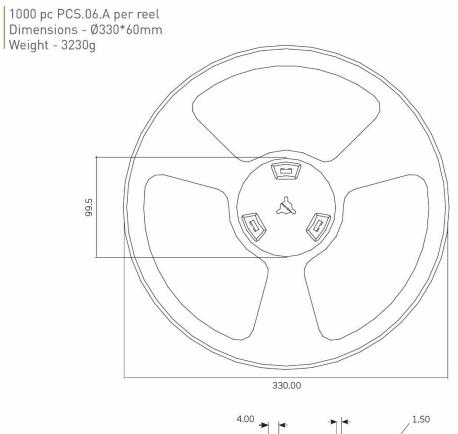


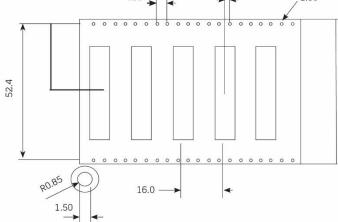
MODEL VIEW



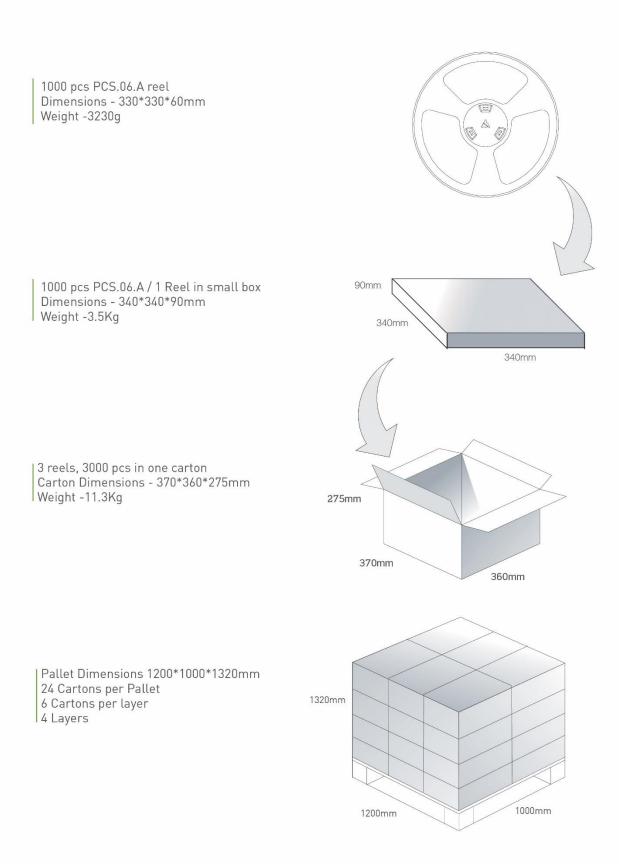
Packaging

6.











Antenna Integration Guide



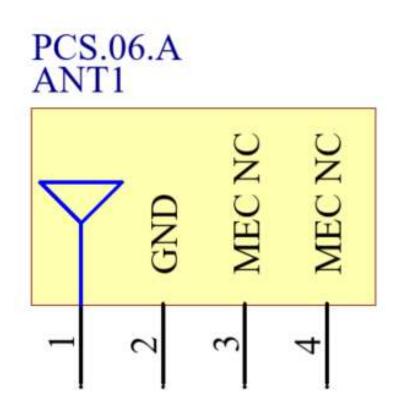
7.



7.1 Schematic and Symbol Definition

The circuit symbol for the antenna is shown below. The antenna has 4 pins with only two pins (Pin 1 and Pin 2) as functional. Pins 3 and 4 are for mechanical strength.

Pin	Description	
1	RF Feed	
2	Ground	
3, 4	Mechanical, Not Connected	



Please note you can download the design files, 3D model, 2D drawings and CST simulation files from the website here:

https://www.taoglas.com/product/havok-pcs-06-2g3g4g-low-profile-smd-antenna-2/



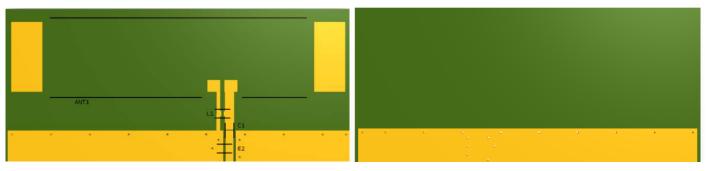
7.2 Antenna Integration

Whatever the size of the PCB, the antenna should ideally be placed on the PCB's shortest side, to take advantage of the ground plane. Optimized matching components can be placed as shown.





The footprint and clearance on the PCB must meet the antenna specification. An example of the PCB layout shows the antenna footprint with clearance. Note the placement of the optimized components. L1 is positioned outside the ground plane and C1 is sitting across the ground plane and the copper clearance area. C2 is optional as a component but it is recommended to include these pads in case they are needed.



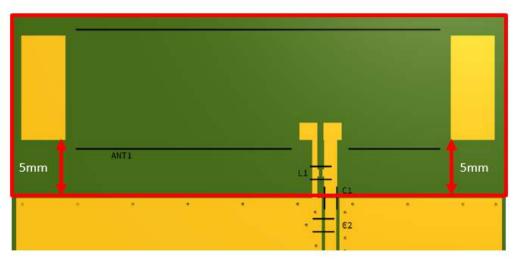
Topside

Bottom Side

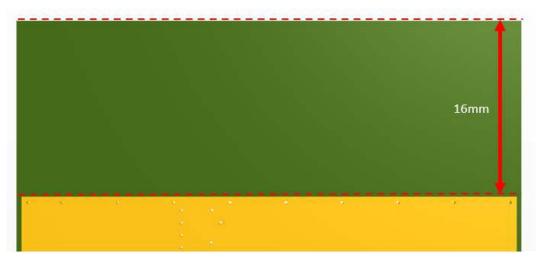


7.4 PCB Clearance

Below shows the antenna footprint and clearance through ALL layers on the PCB. Only the antenna pads and connections to feed and GND are present within this clearance area (marked RED). The clearance area extends to 5mm from the antenna mechanical pads to the ground area. This clearance area includes the bottom side and ALL internal layers on the PCB.



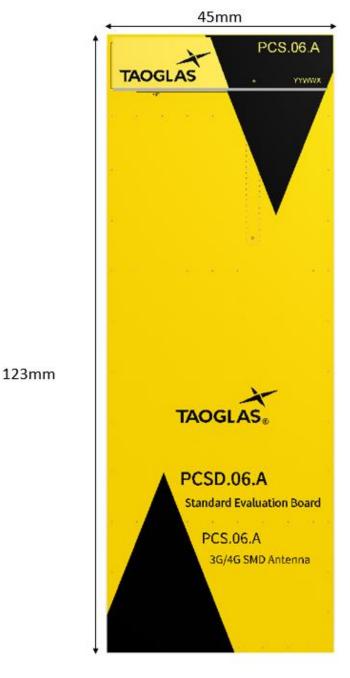
Topside



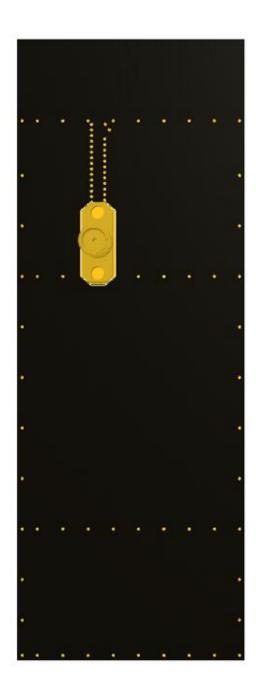
Bottom Side



7.5 Evaluation Board



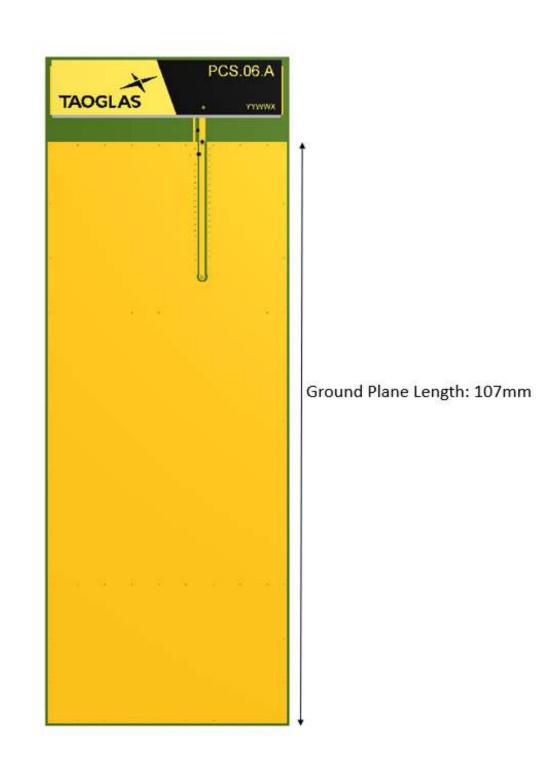
Topside







7.6 Evaluation Board Ground Plane Length

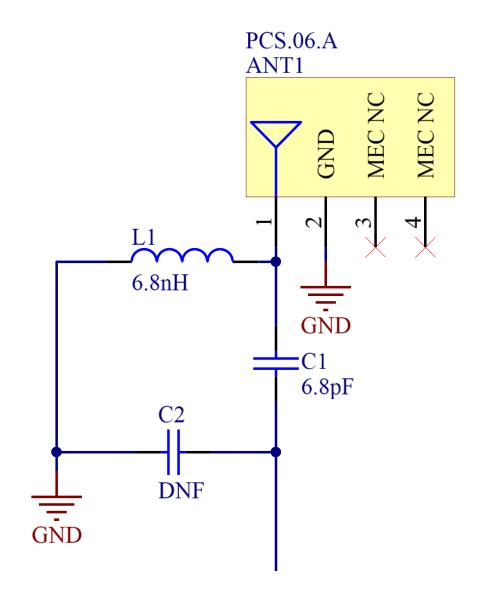




Evaluation Board Matching Circuit

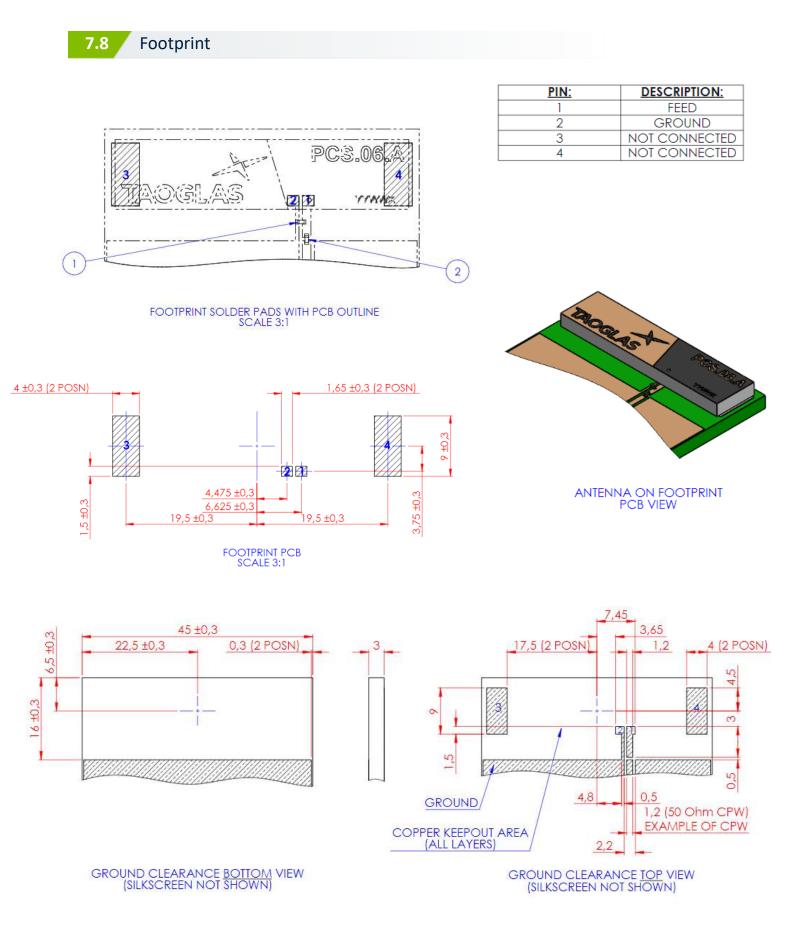
7.7

A matching component (L1) in parallel with the PCS.06.A is required for the antenna to have optimal performance on the evaluation board, located outside of the ground plane in the space specified in the above images. C1 is also required as a matching component for this antenna. C1 is positioned sitting across the ground plane as shown in the above images. Additional matching components may be necessary for your device, so we recommend incorporating extra component footprints, forming a "pi" network, between the cellular module and the edge of the ground plane.



Designator	Туре	Value	Description
L1	Inductor	6.8nH	TDK: MLK1005S Series
C1	Capacitor	6.8pF	Murata:GRM1555 Series
C2	Capacitor	Not Fitted	

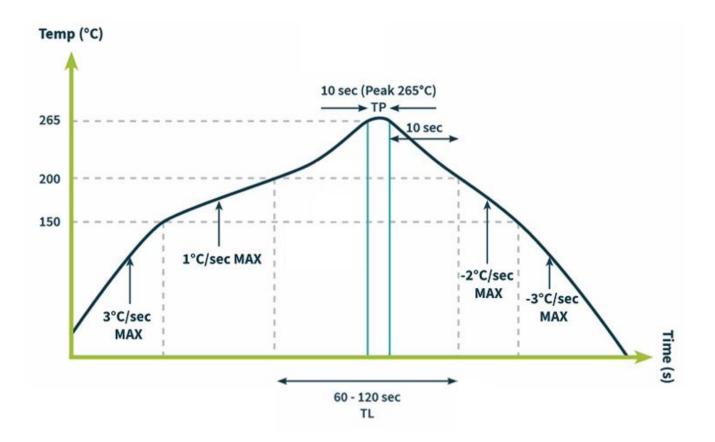






8. Solder Reflow Profile

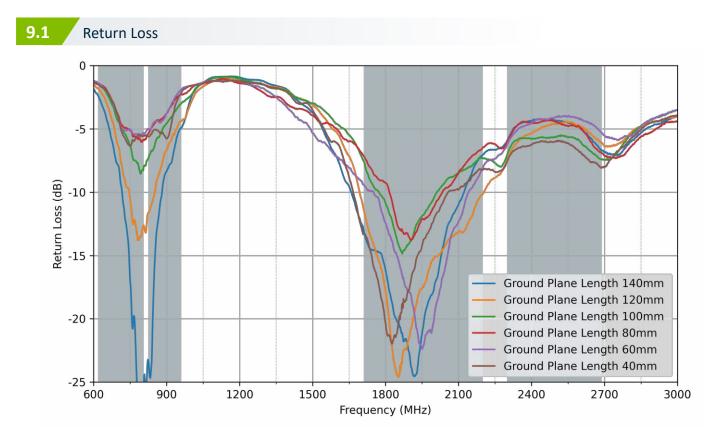
The PCS.06.A can be assembled by following the recommended soldering temperatures are as follows:



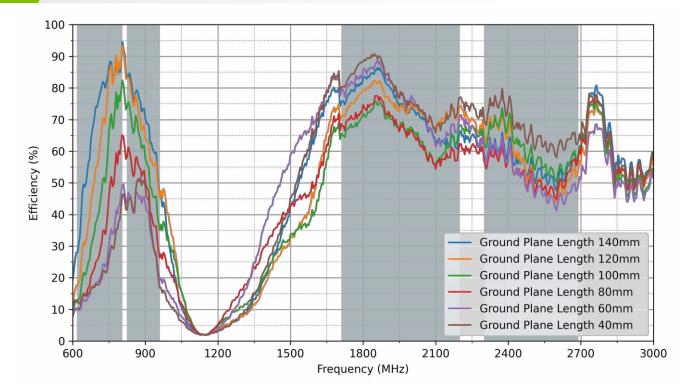
The PCS.06.A is not limited to the number of passes through the reflow process. Smaller components are typically mounted on the first pass, however, we do advise mounting the PCS.06.A when placing larger components on the board during subsequent reflows.

9.







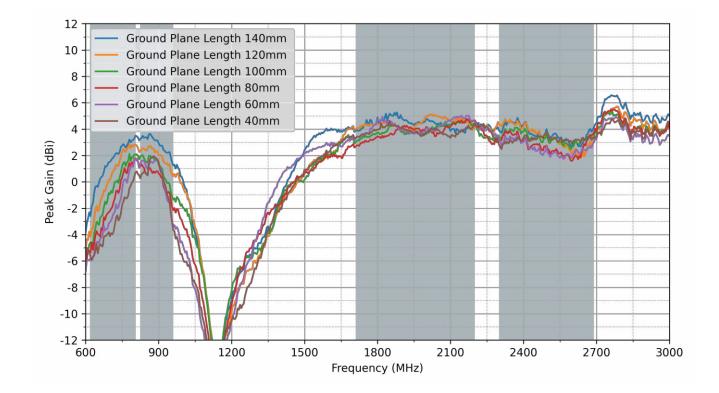


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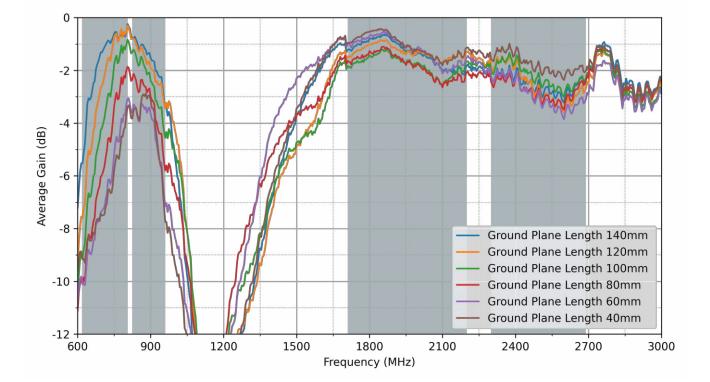


9.3 Peak Gain





Average Gain





Changelog for the datasheet

SPE-13-8-070 – PCS.06.A			
Revision: T (Current	Version)		
Date:	2023-08-08		
Changes:	Update Solder Reflow Profile		
Changes Made by:	Gary West		

Previous Revisions

Revision: S	Revision: N		
Date:	2023-04-28	Date:	
Changes:	Update all test data.	Changes:	
Changes Made by:	Gary West	Changes Made by:	

Revision: R	Revision: M	
Date:	2022-10-18	Date:
Changes:	Update Mechanical Drawing	Changes:
Changes Made by:	Gary West	Changes Made by:

Changes Made by:	Russell Meyler
Revision: M	
Date:	2018-10-23
Changes:	Did not have a description for the bottom pads, nor a diagram for connections. Amended

Updated Imagery Reference ECR-18-8-259

2015-11-19

Revision: Q			
Date:	2022-07-26		
Changes:	Added application note		
Changes Made by:	Gary West		

Revision: L	
Date:	2018-01-30
Changes:	PCN-17-8-181/A
Changes Made by:	Carol Faughnan

David Connolly

Revision: P	
Date:	2021-07-09
Changes:	Updated RF data.
Changes Made by:	Gary West

Date:	2017-06-09
Changes:	Updated with image as per Aliss' request.
Changes Made by:	Andy Mahoney

Revision: O	
Date:	2021-02-22
Changes:	Updated datasheet template and added antenna integration guide.
Changes Made by:	Gary West

Revision: J	
Date:	2017-04-28
Changes:	Added LTE Band Table.
Changes Made by:	Peter Monahan



Revision: I	
Date:	2017-04-14
Changes:	Ammended Drawing
Changes Made by:	Jack Conroy

Revision: B	
Date:	2014-01-16
Changes:	Added Photo
Changes Made by:	Aine Doyle

Revision: H	
Date:	2017-04-04
Changes:	Added LTE Band Table.
Changes Made by:	Peter Monahan

Revision: A (First Release)	
Date:	
Changes:	First Release
Changes Made by:	Technical Writer

Revision: G	
Date:	2017-03-03
Changes:	Updated to include disclaimer, revised packaging as per PCN and general cleaning.
Changes Made by:	Andy Mahoney

Revision: F	
Date:	2015-04-26
Changes:	Comments from John
Changes Made by:	Aine Doyle

Revision: E	
Date:	2015-06-30
Changes:	Added Packaging
Changes Made by:	Aine Doyle

Revision: D	
Date:	2015-05-19
Changes:	Updated Footprint
Changes Made by:	Aine Doyle

Revision: C	
Date:	2014-03-02
Changes:	Added Product Name
Changes Made by:	Aine Doyle





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